Lattice Semiconductor Corporation - LCMXO1200E-3T100C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

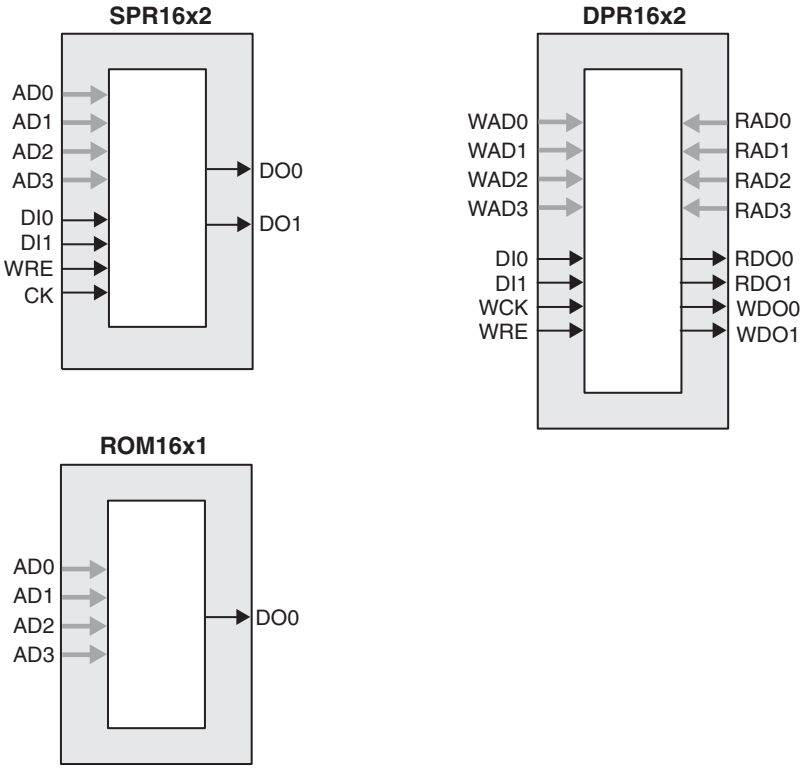
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	73
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200e-3t100c

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from PLL output, clock net, routing/external pin or internal feedback from CLKINTFB port
RST	I	"1" to reset the input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
CLKINTFB	O	Internal feedback source, CLKOP divider output before CLOCKTREE
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

sysMEM Memory

The MachXO1200 and MachXO2280 devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

Table 2-8. I/O Support Device by Device

	MachXO256	MachXO640	MachXO1200	MachXO2280
Number of I/O Banks	2	4	8	8
Type of Input Buffers	Single-ended (all I/O Banks)	Single-ended (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)
Differential Output Emulation Capability	All I/O Banks	All I/O Banks	All I/O Banks	All I/O Banks
PCI Support	No	No	Top side only	Top side only

Table 2-9. Supported Input Standards

	VCCIO (Typ.)				
Input Standard	**3.3V**	**2.5V**	**1.8V**	**1.5V**	**1.2V**
Single Ended Interfaces					
LVTTL	Yes	Yes	Yes	Yes	Yes
LVCMOS33	Yes	Yes	Yes	Yes	Yes
LVCMOS25	Yes	Yes	Yes	Yes	Yes
LVCMOS18			Yes		
LVCMOS15				Yes	
LVCMOS12	Yes	Yes	Yes	Yes	Yes
PCI[1]	Yes				
Differential Interfaces					
BLVDS[2], LVDS[2], LVPECL[2], RSDS[2]	Yes	Yes	Yes	Yes	Yes

1. Top Banks of MachXO1200 and MachXO2280 devices only.
2. MachXO1200 and MachXO2280 devices only.

Table 2-10. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Typ.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA	3.3
LVCMOS33	4mA, 8mA, 12mA, 14mA	3.3
LVCMOS25	4mA, 8mA, 12mA, 14mA	2.5
LVCMOS18	4mA, 8mA, 12mA, 14mA	1.8
LVCMOS15	4mA, 8mA	1.5
LVCMOS12	2mA, 6mA	1.2
LVCMOS33, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVCMOS25, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVCMOS18, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVCMOS15, Open Drain	4mA, 8mA	—
LVCMOS12, Open Drain	2mA, 6mA	—
PCI33[3]	N/A	3.3
Differential Interfaces		
LVDS[1, 2]	N/A	2.5
BLVDS, RSDS[2]	N/A	2.5
LVPECL[2]	N/A	3.3

1. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers.
2. These interfaces can be emulated with external resistors in all devices.
3. Top Banks of MachXO1200 and MachXO2280 devices only.

sysIO Buffer Banks

The number of Banks vary between the devices of this family. Eight Banks surround the two larger devices, the MachXO1200 and MachXO2280 (two Banks per side). The MachXO640 has four Banks (one Bank per side). The smallest member of this family, the MachXO256, has only two Banks.

Each sysIO buffer Bank is capable of supporting multiple I/O standards. Each Bank has its own I/O supply voltage (V_{CCIO}) which allows it to be completely independent from the other Banks. Figure 2-18, Figure 2-18, Figure 2-20 and Figure 2-21 shows the sysIO Banks and their associated supplies for all devices.

the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO "C" devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <10mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1}; MachXO640: V_{CCIO2}; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Table 3-2. BLVDS DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal		Units
		Zo = 45	Zo = 90	
Z_{OUT}	Output impedance	100	100	Ohms
R_{TLEFT}	Left end termination	45	90	Ohms
R_{TRIGHT}	Right end termination	45	90	Ohms
V_{OH}	Output high voltage	1.375	1.48	V
V_{OL}	Output low voltage	1.125	1.02	V
V_{OD}	Output differential voltage	0.25	0.46	V
V_{CM}	Output common mode voltage	1.25	1.25	V
I_{DC}	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

LVPECL

The MachXO family supports the differential LVPECL standard through emulation. This output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The LVPECL input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

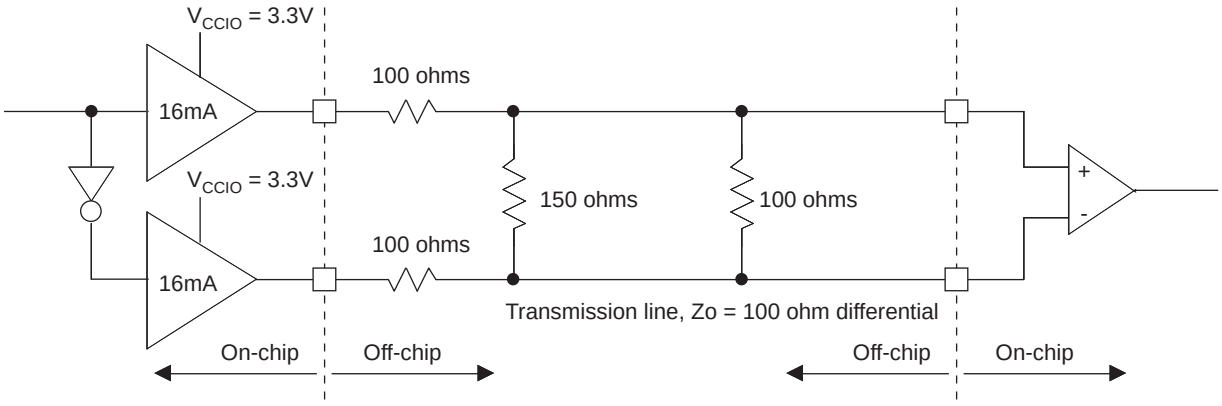


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Nominal	Units
Z_{OUT}	Output impedance	100	Ohms
R_P	Driver parallel resistor	150	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	Ohms
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

MachXO External Switching Characteristics[1]

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Global Clock without PLL)[1]									
t_{PD}	Best Case t_{PD} Through 1 LUT	LCMXO256	—	3.5	—	4.2	—	4.9	ns
		LCMXO640	—	3.5	—	4.2	—	4.9	ns
		LCMXO1200	—	3.6	—	4.4	—	5.1	ns
		LCMXO2280	—	3.6	—	4.4	—	5.1	ns
t_{CO}	Best Case Clock to Output - From PFU	LCMXO256	—	4.0	—	4.8	—	5.6	ns
		LCMXO640	—	4.0	—	4.8	—	5.7	ns
		LCMXO1200	—	4.3	—	5.2	—	6.1	ns
		LCMXO2280	—	4.3	—	5.2	—	6.1	ns
t_{SU}	Clock to Data Setup - To PFU	LCMXO256	1.3	—	1.6	—	1.8	—	ns
		LCMXO640	1.1	—	1.3	—	1.5	—	ns
		LCMXO1200	1.1	—	1.3	—	1.6	—	ns
		LCMXO2280	1.1	—	1.3	—	1.5	—	ns
t_{H}	Clock to Data Hold - To PFU	LCMXO256	-0.3	—	-0.3	—	-0.3	—	ns
		LCMXO640	-0.1	—	-0.1	—	-0.1	—	ns
		LCMXO1200	0.0	—	0.0	—	0.0	—	ns
		LCMXO2280	-0.4	—	-0.4	—	-0.4	—	ns
f_{MAX_IO}	Clock Frequency of I/O and PFU Register	LCMXO256	—	600	—	550	—	500	MHz
		LCMXO640	—	600	—	550	—	500	MHz
		LCMXO1200	—	600	—	550	—	500	MHz
		LCMXO2280	—	600	—	550	—	500	MHz
t_{SKEW_PRI}	Global Clock Skew Across Device	LCMXO256	—	200	—	220	—	240	ps
		LCMXO640	—	200	—	220	—	240	ps
		LCMXO1200	—	220	—	240	—	260	ps
		LCMXO2280	—	220	—	240	—	260	ps

1. General timing numbers based on LVCMOS2.5V, 12 mA.

MachXO Internal Timing Parameters[1]

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t_{LUT4_PFU}	LUT4 delay (A to D inputs to F output)	—	0.28	—	0.34	—	0.39	ns
t_{LUT6_PFU}	LUT6 delay (A to D inputs to OFX output)	—	0.44	—	0.53	—	0.62	ns
t_{LSR_PFU}	Set/Reset to output of PFU	—	0.90	—	1.08	—	1.26	ns
t_{SUM_PFU}	Clock to Mux (M0,M1) input setup time	0.10	—	0.13	—	0.15	—	ns
t_{HM_PFU}	Clock to Mux (M0,M1) input hold time	-0.05	—	-0.06	—	-0.07	—	ns
t_{SUD_PFU}	Clock to D input setup time	0.13	—	0.16	—	0.18	—	ns
t_{HD_PFU}	Clock to D input hold time	-0.03	—	-0.03	—	-0.04	—	ns
t_{CK2Q_PFU}	Clock to Q delay, D-type register configuration	—	0.40	—	0.48	—	0.56	ns
t_{LE2Q_PFU}	Clock to Q delay latch configuration	—	0.53	—	0.64	—	0.74	ns
t_{LD2Q_PFU}	D to Q throughput delay when latch is enabled	—	0.55	—	0.66	—	0.77	ns
PFU Dual Port Memory Mode Timing								
t_{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.56	ns
t_{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.22	—	-0.25	—	ns
t_{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.39	—	ns
t_{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.56	—	-0.65	—	ns
t_{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	0.99	—	ns
t_{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.26	—	-0.30	—	ns
t_{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.47	—	ns
PIO Input/Output Buffer Timing								
t_{IN_PIO}	Input Buffer Delay	—	0.75	—	0.90	—	1.06	ns
t_{OUT_PIO}	Output Buffer Delay	—	1.29	—	1.54	—	1.80	ns
EBR Timing (1200 and 2280 Devices Only)								
t_{CO_EBR}	Clock to output from Address or Data with no output register	—	2.24	—	2.69	—	3.14	ns
t_{COO_EBR}	Clock to output from EBR output Register	—	0.54	—	0.64	—	0.75	ns
t_{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t_{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t_{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.31	—	-0.37	—	ns
t_{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.57	—	ns
t_{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.20	—	-0.23	—	ns
t_{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.36	—	ns
t_{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.27	—	ns
t_{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.16	—	-0.18	—	ns
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.03	—	1.23	—	1.44	ns
PLL Parameters (1200 and 2280 Devices Only)								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

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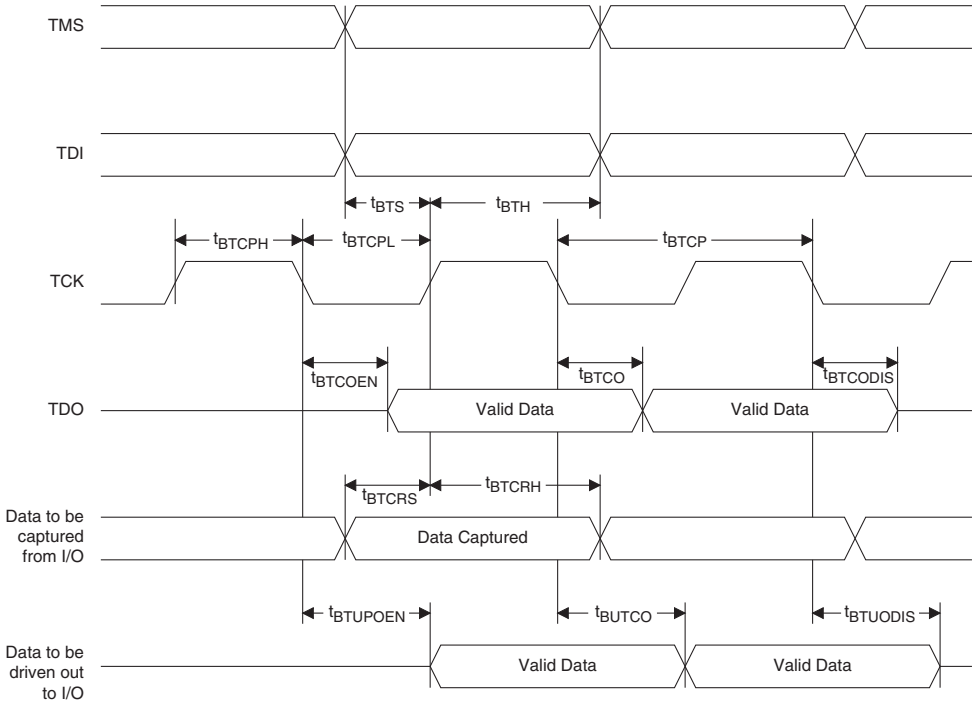
Figure 3-5. JTAG Port Timing Waveforms



Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number]_[A/B/C/D/E/F]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected. Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic. During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V_{CC}	—	VCC - The power supply pins for core logic. Dedicated pins.
V_{CCAUX}	—	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V_{CCIOx}	—	V_{CCIO} - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN[1]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ This pin has a weak internal pull-up, but when unused, an external pull-up to V_{CC} is recommended. When driven low, the device moves into Sleep mode after a specified time.
PLL and Clock Functions (Used as user programmable I/O pins when not used for PLL or clock pins)		
[LOC][0]_PLL[T, C]_IN	—	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
[LOC][0]_PLL[T, C]_FB	—	Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin -Test Data output pin used to shift data out of the device using 1149.1.

1. Applies to MachXO “C” devices only. NC for “E” devices.

Pin Information Summary

Pin Type		LCMXO256C/E		LCMXO640C/E				
		100 TQFP	100 csBGA	100 TQFP	144 TQFP	100 csBGA	132 csBGA	256 caBGA / 256 ftBGA
Single Ended User I/O		78	78	74	113	74	101	159
Differential Pair User I/O[1]		38	38	17	43	17	42	79
Muxed		6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4
Dedicated (Total Without Supplies)		5	5	5	5	5	5	5
VCC		2	2	2	4	2	4	4
VCCAUX		1	1	1	2	1	2	2
VCCIO	Bank0	3	3	2	2	2	2	4
	Bank1	3	3	2	2	2	2	4
	Bank2	—	—	2	2	2	2	4
	Bank3	—	—	2	2	2	2	4
GND		8	8	10	12	10	12	18
NC		0	0	0	0	0	0	52
Single Ended/Differential I/O per Bank	Bank0	41/20	41/20	18/5	29/10	18/5	26/11	42/21
	Bank1	37/18	37/18	21/4	30/11	21/4	27/12	40/20
	Bank2	—	—	14/2	24/9	14/2	21/9	36/18
	Bank3	—	—	21/6	30/13	21/6	27/10	40/20

1. These devices support emulated LVDS outputs.þLVDS inputs are not supported.

Pin Type		LCMXO1200C/E				LCMXO2280C/E				
		100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	100 TQFP	144 TQFP	132 csBGA	256 caBGA / 256 ftBGA	324 ftBGA
Single Ended User I/O		73	113	101	211	73	113	101	211	271
Differential Pair User I/O[1]		27	48	42	105	30	47	41	105	134
Muxed		6	6	6	6	6	6	6	6	6
TAP		4	4	4	4	4	4	4	4	4
Dedicated (Total Without Supplies)		5	5	5	5	5	5	5	5	5
VCC		4	4	4	4	2	4	4	4	6
VCCAUX		2	2	2	2	2	2	2	2	2
VCCIO	Bank0	1	1	1	2	1	1	1	2	2
	Bank1	1	1	1	2	1	1	1	2	2
	Bank2	1	1	1	2	1	1	1	2	2
	Bank3	1	1	1	2	1	1	1	2	2
	Bank4	1	1	1	2	1	1	1	2	2
	Bank5	1	1	1	2	1	1	1	2	2
	Bank6	1	1	1	2	1	1	1	2	2
	Bank7	1	1	1	2	1	1	1	2	2
GND		8	12	12	18	8	12	12	18	24
NC		0	0	0	0	0	0	0	0	0
Single Ended/Differential I/O per Bank	Bank0	10/3	14/6	13/5	26/13	9/3	13/6	12/5	24/12	34/17
	Bank1	8/2	15/7	13/5	28/14	9/3	16/7	14/5	30/15	36/18
	Bank2	10/4	15/7	13/6	26/13	10/4	15/7	13/6	26/13	34/17
	Bank3	11/5	15/7	14/7	28/14	11/5	15/7	14/7	28/14	34/17
	Bank4	8/3	14/5	13/5	27/13	8/3	14/4	13/4	29/14	35/17
	Bank5	5/2	10/4	8/2	22/11	5/2	10/4	8/2	20/10	30/15
	Bank6	10/3	15/6	13/6	28/14	10/4	15/6	13/6	28/14	34/17
	Bank7	11/5	15/6	14/6	26/13	11/5	15/6	14/6	26/13	34/17

1. These devices support on-chip LVDS buffers for left and right I/O Banks.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B1	PL2A	3		T	B1	PL2A	7		T	B1	PL2A	7	LUM0_PLLT_FB_A	T
C1	PL2B	3		C	C1	PL3C	7		T	C1	PL3C	7	LUM0_PLLT_IN_A	T
B2	PL2C	3		T	B2	PL2B	7		C	B2	PL2B	7	LUM0_PLLC_FB_A	C
C2	PL2D	3		C	C2	PL4A	7		T*	C2	PL4A	7		T*
C3	PL3A	3		T	C3	PL3D	7		C	C3	PL3D	7	LUM0_PLLC_IN_A	C
D1	PL3B	3		C	D1	PL4B	7		C*	D1	PL4B	7		C*
D3	PL3D	3			D3	PL4C	7			D3	PL4C	7		
E1	GNDIO3	3			E1	GNDIO7	7			E1	GNDIO7	7		
E2	PL5A	3		T	E2	PL6A	7		T*	E2	PL7A	7		T*
E3	PL5B	3	GSRN	C	E3	PL6B	7	GSRN	C*	E3	PL7B	7	GSRN	C*
F2	PL5D	3			F2	PL6D	7			F2	PL7D	7		
F3	PL6B	3			F3	PL7C	7		T	F3	PL9C	7		T
G1	PL6C	3		T	G1	PL7D	7		C	G1	PL9D	7		C
G2	PL6D	3		C	G2	PL8C	7		T	G2	PL10C	7		T
G3	PL7A	3		T	G3	PL8D	7		C	G3	PL10D	7		C
H2	PL7B	3		C	H2	PL10A	6		T*	H2	PL12A	6		T*
H1	PL7C	3			H1	PL10B	6		C*	H1	PL12B	6		C*
H3	VCC	-			H3	VCC	-			H3	VCC	-		
J1	PL8A	3			J1	PL11B	6			J1	PL14D	6		C
J2	PL8C	3	TSALL		J2	PL11C	6	TSALL	T	J2	PL14C	6	TSALL	T
J3	PL9A	3		T	J3	PL11D	6		C	J3	PL14B	6		
K2	PL9B	3		C	K2	PL12A	6		T*	K2	PL15A	6		T*
K1	PL9C	3			K1	PL12B	6		C*	K1	PL15B	6		C*
L2	GNDIO3	3			L2	GNDIO6	6			L2	GNDIO6	6		
L1	PL10A	3		T	L1	PL14A	6	LLM0_PLLT_FB_A	T*	L1	PL17A	6	LLM0_PLLT_FB_A	T*
L3	PL10B	3		C	L3	PL14B	6	LLM0_PLLC_FB_A	C*	L3	PL17B	6	LLM0_PLLC_FB_A	C*
M1	PL11A	3		T	M1	PL15A	6	LLM0_PLLT_IN_A	T*	M1	PL18A	6	LLM0_PLLT_IN_A	T*
N1	PL11B	3		C	N1	PL16A	6		T	N1	PL19A	6		T
M2	PL11C	3		T	M2	PL15B	6	LLM0_PLLC_IN_A	C*	M2	PL18B	6	LLM0_PLLC_IN_A	C*
P1	PL11D	3		C	P1	PL16B	6		C	P1	PL19B	6		C
P2	GNDIO2	2			P2	GNDIO5	5			P2	GNDIO5	5		
P3	TMS	2	TMS		P3	TMS	5	TMS		P3	TMS	5	TMS	
M3	PB2C	2		T	M3	PB2C	5		T	M3	PB2A	5		T
N3	PB2D	2		C	N3	PB2D	5		C	N3	PB2B	5		C
P4	TCK	2	TCK		P4	TCK	5	TCK		P4	TCK	5	TCK	
M4	PB3B	2			M4	PB3B	5			M4	PB3B	5		
N4	PB3C	2		T	N4	PB4A	5		T	N4	PB4A	5		T
P5	PB3D	2		C	P5	PB4B	5		C	P5	PB4B	5		C
N5	TDO	2	TDO		N5	TDO	5	TDO		N5	TDO	5	TDO	
M5	TDI	2	TDI		M5	TDI	5	TDI		M5	TDI	5	TDI	
N6	PB4E	2		T	N6	PB5C	5			N6	PB6C	5		
P6	VCC	-			P6	VCC	-			P6	VCC	-		
M6	PB4F	2		C	M6	PB6A	5			M6	PB8A	5		
P7	VCCAUX	-			P7	VCCAUX	-			P7	VCCAUX	-		
N7	PB5A	2		T	N7	PB6F	5			N7	PB8F	5		
M7	PB5B	2	PCLK2_1***	C	M7	PB7B	4	PCLK4_1***		M7	PB10F	4	PCLK4_1***	
N8	PB5D	2			N8	PB7C	4		T	N8	PB10C	4		T
P8	PB6A	2		T	P8	PB7D	4		C	P8	PB10D	4		C
M8	PB6B	2	PCLK2_0***	C	M8	PB7F	4	PCLK4_0***		M8	PB10B	4	PCLK4_0***	
N9	PB7A	2		T	N9	PB9A	4		T	N9	PB12A	4		T

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B9	PT7B	0		C	B9	PT9B	1		C	B9	PT12D	1		C
A9	PT7A	0		T	A9	PT9A	1		T	A9	PT12C	1		T
A8	PT6B	0	PCLK0_1***	C	A8	PT7D	1	PCLK1_1***		A8	PT10B	1	PCLK1_1***	
B8	PT6A	0		T	B8	PT7B	1			B8	PT9D	1		
C8	PT5B	0	PCLK0_0***	C	C8	PT6F	0	PCLK1_0***		C8	PT9B	1	PCLK1_0***	
B7	PT5A	0		T	B7	PT6D	0			B7	PT8D	0		
A7	VCCAUX	-			A7	VCCAUX	-			A7	VCCAUX	-		
C7	VCC	-			C7	VCC	-			C7	VCC	-		
A6	PT4D	0		C	A6	PT5D	0		C	A6	PT7B	0		C
B6	PT4C	0		T	B6	PT5C	0		T	B6	PT7A	0		T
C6	PT3F	0		C	C6	PT5B	0		C	C6	PT6D	0		
B5	PT3E	0		T	B5	PT5A	0		T	B5	PT6E	0		T
A5	PT3D	0			A5	PT4B	0			A5	PT6F	0		C
B4	GNDIO0	0			B4	GNDIO0	0			B4	GNDIO0	0		
A4	PT3B	0			A4	PT3D	0		C	A4	PT4B	0		C
C4	PT2F	0			C4	PT3C	0		T	C4	PT4A	0		T
A3	PT2D	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2C	0		T	A2	PT2B	0		C	A2	PT2B	0		C
B3	PT2B	0		C	B3	PT3A	0		T	B3	PT3A	0		T
A1	PT2A	0		T	A1	PT2A	0		T	A1	PT2A	0		T
F1	GND	-			F1	GND	-			F1	GND	-		
P9	GND	-			P9	GND	-			P9	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
C9	GND	-			C9	GND	-			C9	GND	-		
C5	VCCIO0	0			C5	VCCIO0	0			C5	VCCIO0	0		
B11	VCCIO0	0			B11	VCCIO1	1			B11	VCCIO1	1		
E12	VCCIO1	1			E12	VCCIO2	2			E12	VCCIO2	2		
L12	VCCIO1	1			L12	VCCIO3	3			L12	VCCIO3	3		
M10	VCCIO2	2			M10	VCCIO4	4			M10	VCCIO4	4		
N2	VCCIO2	2			N2	VCCIO5	5			N2	VCCIO5	5		
D2	VCCIO3	3			D2	VCCIO7	7			D2	VCCIO7	7		
K3	VCCIO3	3			K3	VCCIO6	6			K3	VCCIO6	6		

*Supports true LVDS outputs.
**NC for “E” devices.
***Primary clock inputs arer single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
-	-				VCCIO4	VCCIO4	4			VCCIO4	VCCIO4	4		
-	-				GND	GNDIO4	4			GND	GNDIO4	4		
M10	PB6A	2		T	M10	PB7E	4		T	M10	PB10A	4		T
R9	PB6C	2		T	R9	PB8A	4		T	R9	PB11C	4		T
R10	PB6D	2		C	R10	PB8B	4		C	R10	PB11D	4		C
T10	PB7C	2		T	T10	PB8C	4		T	T10	PB12A	4		T
T11	PB7D	2		C	T11	PB8D	4		C	T11	PB12B	4		C
N10	NC				N10	PB8E	4		T	N10	PB12C	4		T
N11	NC				N11	PB8F	4		C	N11	PB12D	4		C
VCCIO2	VCCIO2	2			VCCIO4	VCCIO4	4			VCCIO4	VCCIO4	4		
GND	GNDIO2	2			GND	GNDIO4	4			GND	GNDIO4	4		
R11	PB7E	2		T	R11	PB9A	4		T	R11	PB13A	4		T
R12	PB7F	2		C	R12	PB9B	4		C	R12	PB13B	4		C
P11	PB8A	2		T	P11	PB9C	4		T	P11	PB13C	4		T
P12	PB8B	2		C	P12	PB9D	4		C	P12	PB13D	4		C
T13	PB8C	2		T	T13	PB9E	4		T	T13	PB14A	4		T
T12	PB8D	2		C	T12	PB9F	4		C	T12	PB14B	4		C
R13	PB9A	2		T	R13	PB10A	4		T	R13	PB14C	4		T
R14	PB9B	2		C	R14	PB10B	4		C	R14	PB14D	4		C
GND	GND	-			GND	GND	-			GND	GND	-		
T14	PB9C	2		T	T14	PB10C	4		T	T14	PB15A	4		T
T15	PB9D	2		C	T15	PB10D	4		C	T15	PB15B	4		C
P13**	SLEEPN	-	SLEEPN		P13**	SLEEPN	-	SLEEPN		P13**	SLEEPN	-	SLEEPN	
P14	PB9F	2			P14	PB10F	4			P14	PB15D	4		
R15	NC				R15	PB11A	4		T	R15	PB16A	4		T
R16	NC				R16	PB11B	4		C	R16	PB16B	4		C
P15	NC				P15	PB11C	4		T	P15	PB16C	4		T
P16	NC				P16	PB11D	4		C	P16	PB16D	4		C
VCCIO2	VCCIO2	2			VCCIO4	VCCIO4	4			VCCIO4	VCCIO4	4		
GND	GNDIO2	2			GND	GNDIO4	4			GND	GNDIO4	4		
GND	GNDIO1	1			GND	GNDIO3	3			GND	GNDIO3	3		
VCCIO1	VCCIO1	1			VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
M11	NC				M11	PR16B	3		C	M11	PR20B	3		C
L11	NC				L11	PR16A	3		T	L11	PR20A	3		T
N12	NC				N12	PR15B	3		C*	N12	PR18B	3		C*
N13	NC				N13	PR15A	3		T*	N13	PR18A	3		T*
M13	NC				M13	PR14D	3		C	M13	PR17D	3		C
M12	NC				M12	PR14C	3		T	M12	PR17C	3		T
N14	PR11D	1		C	N14	PR14B	3		C*	N14	PR17B	3		C*
N15	PR11C	1		T	N15	PR14A	3		T*	N15	PR17A	3		T*
L13	PR11B	1		C	L13	PR13D	3		C	L13	PR16D	3		C
L12	PR11A	1		T	L12	PR13C	3		T	L12	PR16C	3		T
M14	PR10B	1		C	M14	PR13B	3		C*	M14	PR16B	3		C*
VCCIO1	VCCIO1	1			VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
GND	GNDIO1	1			GND	GNDIO3	3			GND	GNDIO3	3		
L14	PR10A	1		T	L14	PR13A	3		T*	L14	PR16A	3		T*
N16	PR10D	1		C	N16	PR12D	3		C	N16	PR15D	3		C
M16	PR10C	1		T	M16	PR12C	3		T	M16	PR15C	3		T
M15	PR9D	1		C	M15	PR12B	3		C*	M15	PR15B	3		C*
L15	PR9C	1		T	L15	PR12A	3		T*	L15	PR15A	3		T*
L16	PR9B	1		C	L16	PR11D	3		C	L16	PR14D	3		C
K16	PR9A	1		T	K16	PR11C	3		T	K16	PR14C	3		T
K13	PR8D	1		C	K13	PR11B	3		C*	K13	PR14B	3		C*

LCMXO2280 Logic Signal Connections: 324 ftBGA

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
GND	GNDIO7	7		
VCCIO7	VCCIO7	7		
D4	PL2A	7	LUM0_PLLT_FB_A	T
F5	PL2B	7	LUM0_PLLC_FB_A	C
B3	PL3A	7		T*
C3	PL3B	7		C*
E4	PL3C	7	LUM0_PLLT_IN_A	T
G6	PL3D	7	LUM0_PLLC_IN_A	C
A1	PL4A	7		T*
B1	PL4B	7		C*
F4	PL4C	7		T
VCC	VCC	-		
E3	PL4D	7		C
D2	PL5A	7		T*
D3	PL5B	7		C*
G5	PL5C	7		T
F3	PL5D	7		C
C2	PL6A	7		T*
VCCIO7	VCCIO7	7		
GND	GNDIO7	7		
C1	PL6B	7		C*
H5	PL6C	7		T
G4	PL6D	7		C
E2	PL7A	7		T*
D1	PL7B	7	GSRN	C*
J6	PL7C	7		T
H4	PL7D	7		C
F2	PL8A	7		T*
E1	PL8B	7		C*
GND	GND	-		
J3	PL8C	7		T
J5	PL8D	7		C
G3	PL9A	7		T*
H3	PL9B	7		C*
K3	PL9C	7		T
K5	PL9D	7		C
F1	PL10A	7		T*
VCCIO7	VCCIO7	7		
GND	GNDIO7	7		
G1	PL10B	7		C*
K4	PL10C	7		T
K6	PL10D	7		C

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
G2	PL11A	6		T*
H2	PL11B	6		C*
L3	PL11C	6		T
L5	PL11D	6		C
H1	PL12A	6		T*
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
J2	PL12B	6		C*
L4	PL12C	6		T
L6	PL12D	6		C
K2	PL13A	6		T*
K1	PL13B	6		C*
J1	PL13C	6		T
VCC	VCC	-		
L2	PL13D	6		C
M5	PL14D	6		C
M3	PL14C	6	TSALL	T
L1	PL14B	6		C*
M2	PL14A	6		T*
M1	PL15A	6		T*
N1	PL15B	6		C*
M6	PL15C	6		T
M4	PL15D	6		C
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
P1	PL16A	6		T*
P2	PL16B	6		C*
N3	PL16C	6		T
N4	PL16D	6		C
GND	GND	-		
T1	PL17A	6	LLM0_PLLT_FB_A	T*
R1	PL17B	6	LLM0_PLLC_FB_A	C*
P3	PL17C	6		T
N5	PL17D	6		C
R3	PL18A	6	LLM0_PLLT_IN_A	T*
R2	PL18B	6	LLM0_PLLC_IN_A	C*
P4	PL19A	6		T
N6	PL19B	6		C
U1	PL20A	6		T
VCCIO6	VCCIO6	6		
GND	GNDIO6	6		
GND	GNDIO5	5		
VCCIO5	VCCIO5	5		

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- Thermal Management document
- TN1090 - Power Estimation and Management for MachXO Devices
- Power Calculator tool included with the Lattice ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

MachXO Family Data Sheet Ordering Information

June 2013 Data Sheet DS1002

Part Number Description

LCMXO XXXX X – X XXXXXX X XX

Device Family
MachXO PLD

Logic Capacity
256 LUTs = 256
640 LUTs = 640
1200 LUTs = 1200
2280 LUTs = 2280

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked as described.

Speed
3 = Slowest
4
5 = Fastest

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
M100 = 100-ball csBGA
M132 = 132-ball csBGA
B256 = 256-ball caBGA
FT256 = 256-ball ftBGA
FT324 = 324-ball ftBGA

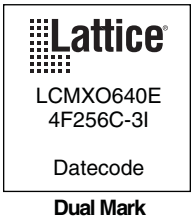
TN100 = 100-pin Lead-Free TQFP
TN144 = 144-pin Lead-Free TQFP
MN100 = 100-ball Lead-Free csBGA
MN132 = 132-ball Lead-Free csBGA
BN256 = 256-ball Lead-Free caBGA
FTN256 = 256-ball Lead-Free ftBGA
FTN324 = 324-ball Lead-Free ftBGA

Grade
C = Commercial
I = Industrial

ES = Engineering Sample
Blank = Production Device

Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device.þFor example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade.þThe slowest commercial speed grade does not have industrial markings.þ The markings appears as follows:



Dual Mark

Conventional Packaging

Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3T100C	256	1.8V/2.5V/3.3V	78	-3	TQFP	100	COM
LCMXO256C-4T100C	256	1.8V/2.5V/3.3V	78	-4	TQFP	100	COM
LCMXO256C-5T100C	256	1.8V/2.5V/3.3V	78	-5	TQFP	100	COM
LCMXO256C-3M100C	256	1.8V/2.5V/3.3V	78	-3	csBGA	100	COM
LCMXO256C-4M100C	256	1.8V/2.5V/3.3V	78	-4	csBGA	100	COM
LCMXO256C-5M100C	256	1.8V/2.5V/3.3V	78	-5	csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3T100C	640	1.8V/2.5V/3.3V	74	-3	TQFP	100	COM
LCMXO640C-4T100C	640	1.8V/2.5V/3.3V	74	-4	TQFP	100	COM
LCMXO640C-5T100C	640	1.8V/2.5V/3.3V	74	-5	TQFP	100	COM
LCMXO640C-3M100C	640	1.8V/2.5V/3.3V	74	-3	csBGA	100	COM
LCMXO640C-4M100C	640	1.8V/2.5V/3.3V	74	-4	csBGA	100	COM
LCMXO640C-5M100C	640	1.8V/2.5V/3.3V	74	-5	csBGA	100	COM
LCMXO640C-3T144C	640	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO640C-4T144C	640	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO640C-5T144C	640	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO640C-3M132C	640	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO640C-4M132C	640	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO640C-5M132C	640	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO640C-3B256C	640	1.8V/2.5V/3.3V	159	-3	caBGA	256	COM
LCMXO640C-4B256C	640	1.8V/2.5V/3.3V	159	-4	caBGA	256	COM
LCMXO640C-5B256C	640	1.8V/2.5V/3.3V	159	-5	caBGA	256	COM
LCMXO640C-3FT256C	640	1.8V/2.5V/3.3V	159	-3	ftBGA	256	COM
LCMXO640C-4FT256C	640	1.8V/2.5V/3.3V	159	-4	ftBGA	256	COM
LCMXO640C-5FT256C	640	1.8V/2.5V/3.3V	159	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3T100C	1200	1.8V/2.5V/3.3V	73	-3	TQFP	100	COM
LCMXO1200C-4T100C	1200	1.8V/2.5V/3.3V	73	-4	TQFP	100	COM
LCMXO1200C-5T100C	1200	1.8V/2.5V/3.3V	73	-5	TQFP	100	COM
LCMXO1200C-3T144C	1200	1.8V/2.5V/3.3V	113	-3	TQFP	144	COM
LCMXO1200C-4T144C	1200	1.8V/2.5V/3.3V	113	-4	TQFP	144	COM
LCMXO1200C-5T144C	1200	1.8V/2.5V/3.3V	113	-5	TQFP	144	COM
LCMXO1200C-3M132C	1200	1.8V/2.5V/3.3V	101	-3	csBGA	132	COM
LCMXO1200C-4M132C	1200	1.8V/2.5V/3.3V	101	-4	csBGA	132	COM
LCMXO1200C-5M132C	1200	1.8V/2.5V/3.3V	101	-5	csBGA	132	COM
LCMXO1200C-3B256C	1200	1.8V/2.5V/3.3V	211	-3	caBGA	256	COM
LCMXO1200C-4B256C	1200	1.8V/2.5V/3.3V	211	-4	caBGA	256	COM
LCMXO1200C-5B256C	1200	1.8V/2.5V/3.3V	211	-5	caBGA	256	COM
LCMXO1200C-3FT256C	1200	1.8V/2.5V/3.3V	211	-3	ftBGA	256	COM
LCMXO1200C-4FT256C	1200	1.8V/2.5V/3.3V	211	-4	ftBGA	256	COM
LCMXO1200C-5FT256C	1200	1.8V/2.5V/3.3V	211	-5	ftBGA	256	COM

Date	Version	Section	Change Summary
April 2006 (cont.)	02.0 (cont.)	Architecture (cont.)	"Top View of the MachXO1200 Device" figure updated.
			"Top View of the MachXO640 Device" figure updated.
			"Top View of the MachXO256 Device" figure updated.
			"Slice Diagram" figure updated.
			Slice Signal Descriptions table updated.
			Routing section updated.
			sysCLOCK Phase Lockecd Loops (PLLs) section updated.
			PLL Diagram updated.
			PLL Signal Descriptions table updated.
			sysMEM Memory section has been updated.
			PIO Groups section has been updated.
			PIO section has been updated.
			MachXO PIO Block Diagram updated.
			Supported Input Standards table updated.
			MachXO Configuration and Programming diagram updated.
		DC and Switching Characteristics	Recommended Operating Conditions table - footnotes updated.
			MachXO256 and MachXO640 Hot Socketing Specifications - footnotes updated.
			Added MachXO1200 and MachXO2280 Hot Socketing Specifications table.
			DC Electrical Characteristics, footnotes have been updated.
			Supply Current (Sleep Mode) table has been updated, removed "4W" references. Footnotes have been updated.
			Supply Current (Standby) table and associated footnotes updated.
			Intialization Supply Current table and footnotes updated.
			Programming and Erase Flash Supply Current table and associated footnotes have been updatd.
			Register-to-Register Performance table updated (rev. A 0.19).
			MachXO External Switching Characteristics updated (rev. A 0.19).
			MachXO Internal Timing Parameters updated (rev. A 0.19).
			MachXO Family Timing Adders updated (rev. A 0.19).
			sysCLOCK Timing updated (rev. A 0.19).
			MachXO "C" Sleep Mode Timing updated (A 0.19).
			JTAG Port Timing Specification updated (rev. A 0.19).
			Test Fixture Required Components table updated.
		Pinout Information	Signal Descriptions have been updated.
			Pin Information Summary has been updated. Footnote has been added.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connections have been updated (PCLKTx_x --> PCLKx_x)
		Ordering Information	Removed "4W" references.
			Added 256-ftBGA Ordering Part Numbers for MachXO640.
May 2006	02.1	Pinout Information	Removed [LOC][0]_PLL_RST from Signal Description table.
			PCLK footnote has been added to all appropriate pins.
August 2006	02.2	Multiple	Removed 256 fpBGA information for MachXO640.